



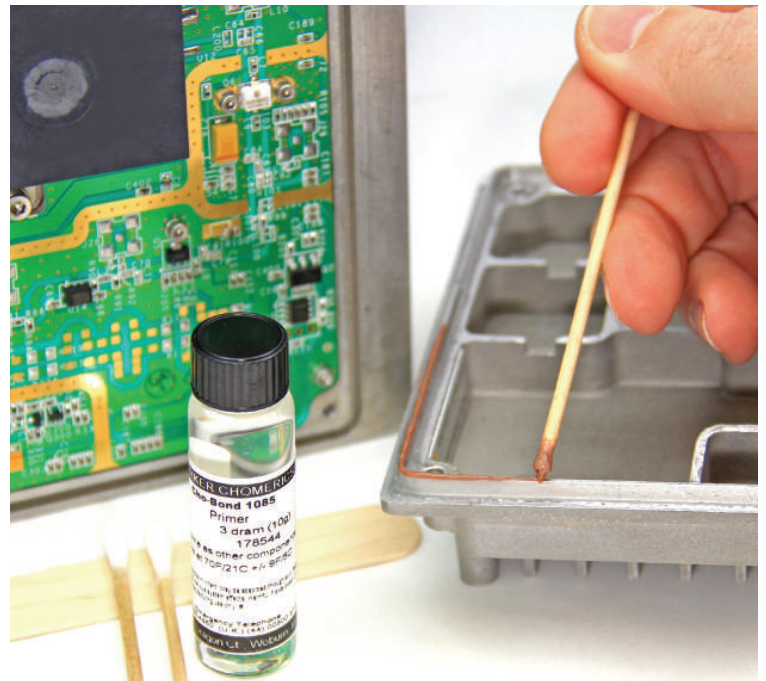
CHO-BOND 1029

TWO COMPONENT FLEXIBLE ELECTRICALLY CONDUCTIVE SILICONE ADHESIVE



CHO-BOND 1029 is a silver plated copper filled, two-component conductive silicone designed for applications where a flexible, strong, conductive electrical bond must be achieved. CHO-BOND 1029 greatly simplifies the problem of bonding conductive silicone EMI gaskets to metal substrates. It is formulated for relatively small bond lines (less than 0.010 inches (0.25mm)), and should not be used as an EMI caulk where bond lines are greater than 0.10 inches (0.25 mm). Low volatile organic compounds (VOCs) and minimal shrinkage upon curing make CHO-BOND 1029 a good choice for a variety of commercial and military applications. Curing of CHO-BOND 1029 can be achieved in as little as 30 minutes with heat to minimize equipment downtime and increase manufacturing throughput. CHO-BOND 1029 is supplied as a two component system, one part liquid and one part wet powder solid. For optimum mixing and material performance, the sand-like solid part should be added incrementally to the liquid part and mixed slowly over a 10 minute time period.

For best adhesion results, CHO-BOND 1029 should be used in conjunction with CHO-SHIELD 1085 primer. Typical applications include bonding, repair, and attachment of EMI gaskets, and sealing around EMI vents and windows.



Features and Benefits:

- Two component
- Silver plated copper filler
- Low VOCs
- Heat cure silicone
- Non corrosive cure mechanism
- Thick paste
- Fast heat cure, increases throughput, minimizes equipment downtime.
- Good conductivity 0.060 ohm-cm.
- Minimal shrinkage.
- Flexible, 120 minute working life, > 450 psi lap shear strength, 24 hr handling time at room temperature, wide range of application temperatures. 1 week for full cure.
- No corrosive by-products generated during curing to damage substrate.
- Can be used on overhead or vertical surfaces.

PROCESSING

Cho Bond 1029 should be mixed to the following procedure:

1. Weigh out 1.0 parts of 1029A and 2.5 parts of 1029B.
2. Pour 1029A from its container onto a smooth aluminium, plexiglass or other suitable large surface for adequate mixing.
(For a 3oz. / 85g batch, mixing board should be at least 8in. x 8in. (20.3cm x 20.3cm))
3. Blend 1029B into 1029A as follows:
 - a) add 33% of 1029B and mix until homogenous.
 - b) add another 33% of 1029B and mix until homogenous.
 - c) add another 16.5% of 1029B and mix until homogenous.
 - d) add balance of 1029B and mix until homogenous. Pot life is now 2 hours at 70°F (21°C).

MIXING INSTRUCTIONS

Mix 1029B into 1029A with a folding action until the material is massed. Then mix by spreading the massed material across the board and recollecting on the spatula. This wiping action will produce a smooth, easily spreadable material. The adhesive is homogenous when silver streaks are no longer visible in the mix.

APPLICATION

Mixed Cho Bond 1029 may be applied by the use of a spatula or by loading the compound into an air activated caulking cartridge and applying with appropriate nozzle, followed by spreading with a spatula.

BONDING PROCEDURE

Cho Bond 1029 should be applied to a solvent (TCE, PCE or acetone) cleaned surface.

With a clean, primer dampened cloth, wipe a very thin coating of Primer 1085 or 1087 primer onto the cleaned metal and air dry for 30 minutes at room temperature. Cho Bond 1029 may then be applied to the metal part such that the adhesive thickness will be 5 to 10 mils. The conductive silicone rubber gasket, cleaned with denatured ethanol, may now be applied to the Cho Bond 1029 coated metal surface. It is necessary to apply a pressure of 2-3 psi perpendicular to the bond plane during cure.
Recommended thickness 0.2mm.

CURING SCHEDULE

Cho Bond may be cured according to the following schedule:

30 minutes	250°F	(149°C)
45 minutes	200°F	(93°C)
60 minutes	150°F	(66°C)
1 week	75°F	(24°C)

